

1. General description

Planar passivated sensitive gate four quadrant triac in a SOT78 (TO-220AB) plastic package intended for use in general purpose bidirectional switching and phase control applications. This sensitive gate "series E" triac is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

2. Features and benefits

- High blocking voltage capability
- Direct triggering from low power drivers and logic ICs
- Planar passivated for voltage ruggedness and reliability
- Triggering in all four quadrants
- Low holding current for low current loads and lowest EMI at commutation
- Sensitive gate

3. Applications

- General purpose motor control
- General purpose switching

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
Absolute maximum rating						
V_{DRM}	repetitive peak off-state voltage		600			V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 102^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	8			A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$; $t_b = 20\text{ ms}$; Fig. 4 ; Fig. 5	65			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G+; $T_j = 25^\circ\text{C}$; Fig. 7	-	2.5	10	mA
		$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2+ G-; $T_j = 25^\circ\text{C}$; Fig. 7	-	4	10	mA
		$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G-; $T_j = 25^\circ\text{C}$; Fig. 7	-	5	10	mA
		$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; T2- G+; $T_j = 25^\circ\text{C}$; Fig. 7	-	11	25	mA
I_H	holding current	$V_D = 12\text{ V}$; $T_j = 25^\circ\text{C}$; Fig. 9	-	2.5	20	mA

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		
2	T2	main terminal 2		
3	G	gate		
mb	T2	mounting base; main terminal 2		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BT137-600E	TO220	BT137-600E,127	Tube	50	SOT78	13-Jun-2008
BT137-600E/DG		BT137-600E/DG	Tube	50	SOT78 (Halogen free)	13-Jun-2008

7. Marking

Table 4. Marking codes

Type number	Marking codes	
	Assembly factory: A	Assembly factory: d
BT137-600E	BT137 600E PJAxXX XX	-
BT137-600E/DG	BT137 600EDG PJAxXX XX	BT137 600EDG PJdXXX XX

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		600	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 102^\circ\text{C}$; Fig 1 ; Fig 2 ; Fig 3	8	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25^\circ\text{C}$; $t_p = 20\text{ ms}$; Fig 4 ; Fig 5	65	A
		full sine wave; $T_{j(init)} = 25^\circ\text{C}$; $t_p = 16.7\text{ ms}$	71	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; SIN	21	A^2s
dI/dt	rate of rise of on-state current	$I_G = 20\text{ mA}$; T2+ G+	50	$\text{A}/\mu\text{s}$
		$I_G = 20\text{ mA}$; T2+ G-	50	$\text{A}/\mu\text{s}$
		$I_G = 20\text{ mA}$; T2- G-	50	$\text{A}/\mu\text{s}$
		$I_G = 50\text{ mA}$; T2- G+	10	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current		2	A
P_{GM}	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
T_{stg}	storage temperature		-40 to 150	$^\circ\text{C}$
T_j	junction temperature		125	$^\circ\text{C}$

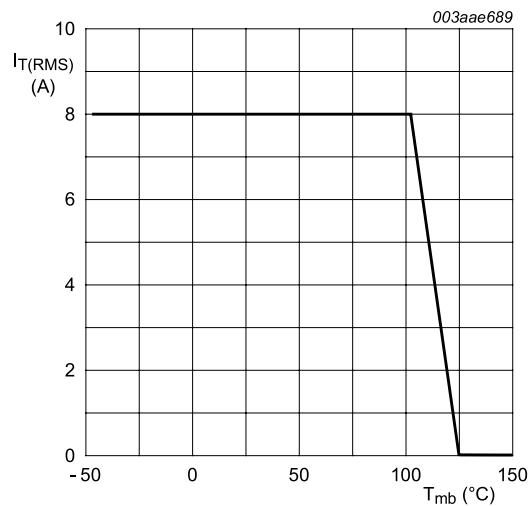
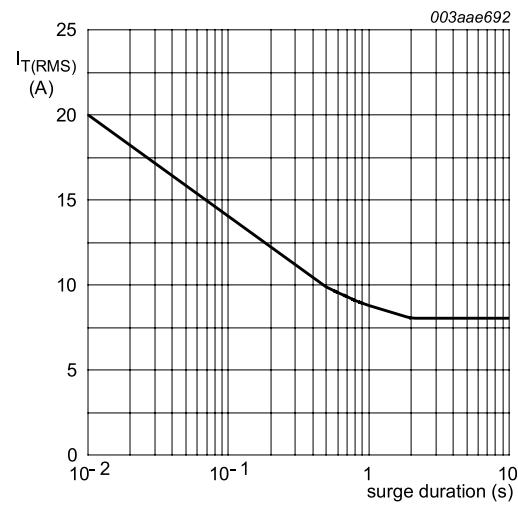
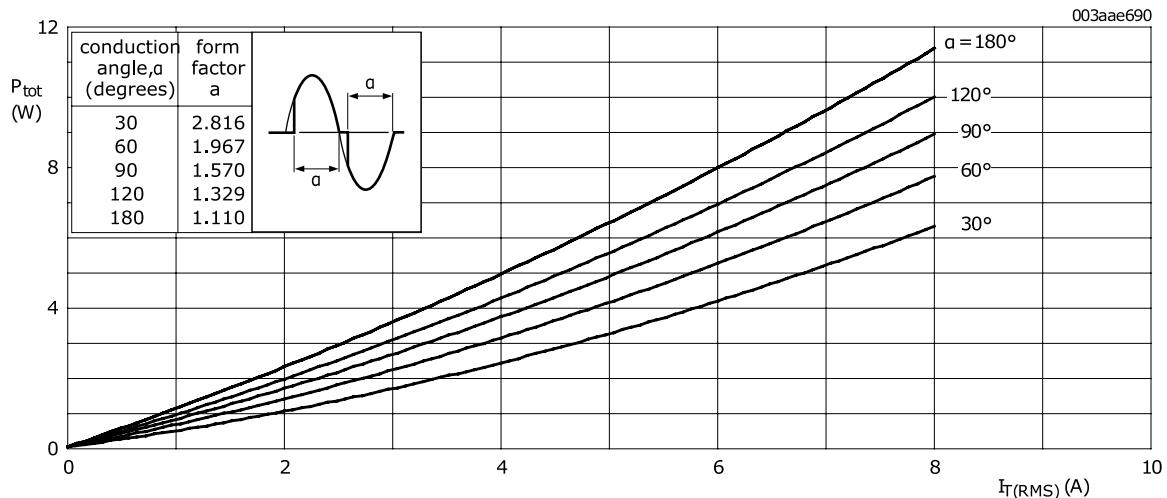


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz; $T_{mb} \leq 102$ °C
Fig. 2. RMS on-state current as a function of surge duration; maximum values



α = conduction angle
 a = form factor = $I_{T(RMS)} / I_{T(AV)}$

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

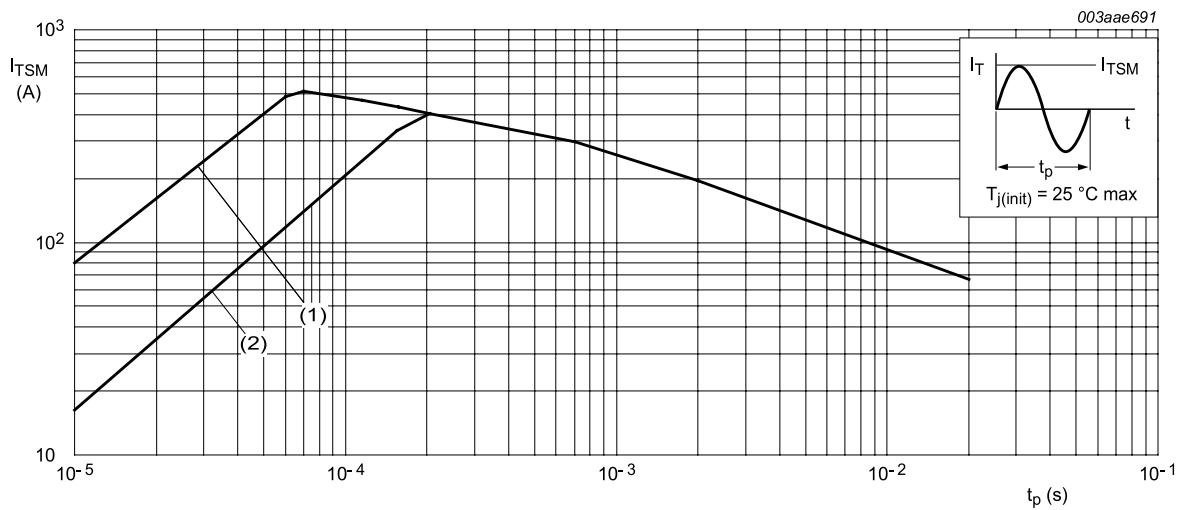


Fig. 4. Non-repetitive peak on-state current as a function of pulse width; maximum values

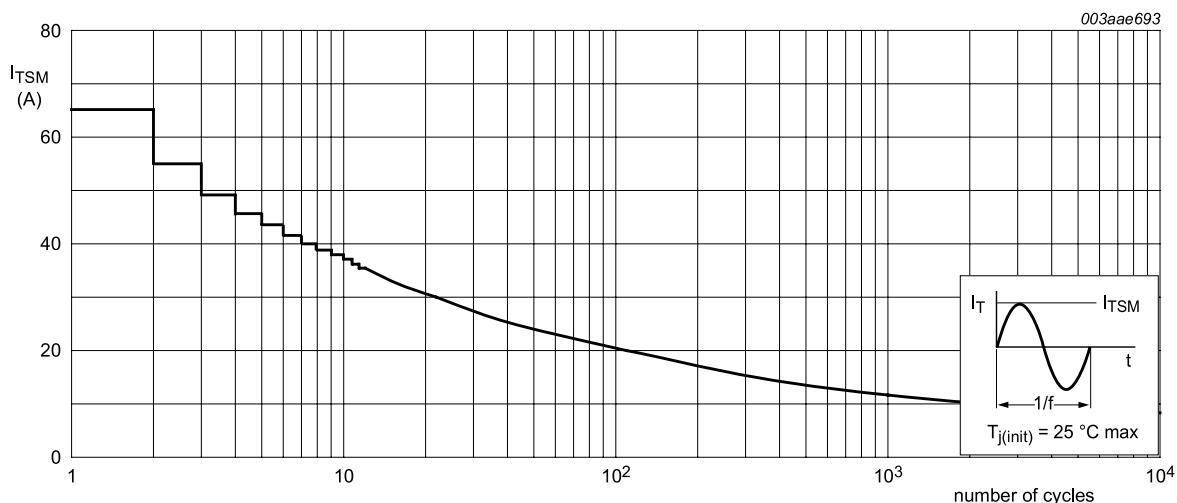


Fig. 5. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	full cycle; Fig. 6		-	-	2	K/W
		half cycle; Fig. 6		-	-	2.4	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		-	60	-	K/W

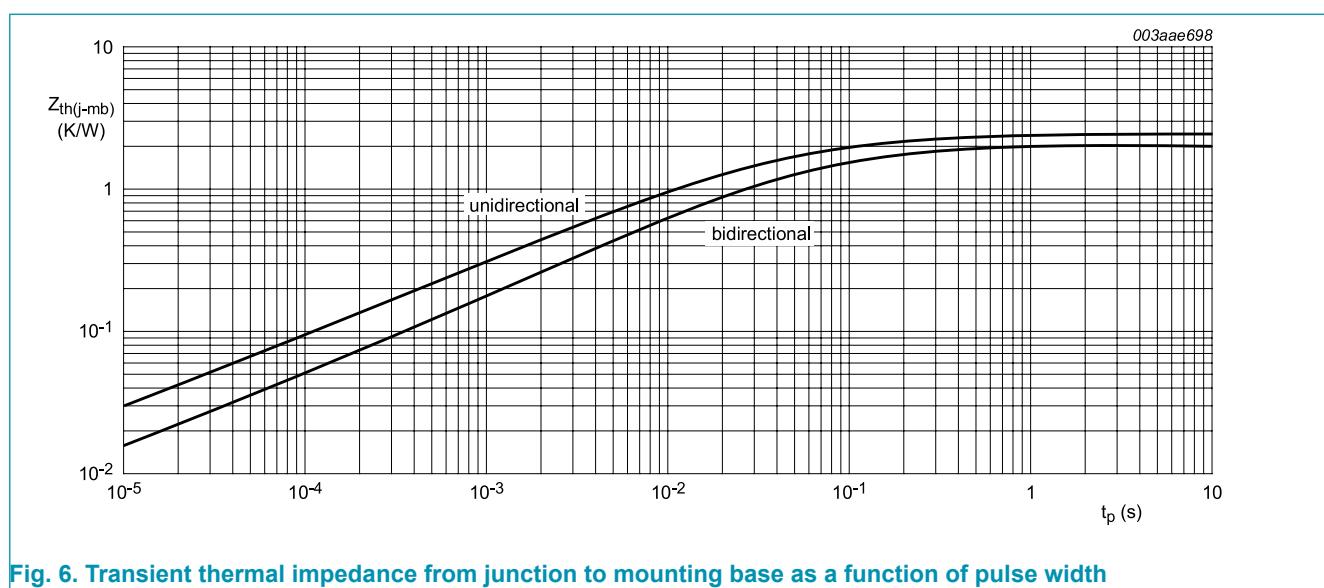


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse width

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_2+ G+; T_J = 25^\circ\text{C}$; Fig. 7		-	2.5	10	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_2+ G-; T_J = 25^\circ\text{C}$; Fig. 7		-	4	10	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_2- G-; T_J = 25^\circ\text{C}$; Fig. 7		-	5	10	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_2- G+; T_J = 25^\circ\text{C}$; Fig. 7		-	11	25	mA
I_L	latching current	$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_2+ G+; T_J = 25^\circ\text{C}$; Fig. 8		-	3	25	mA
		$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_2+ G-; T_J = 25^\circ\text{C}$; Fig. 8		-	14	35	mA
		$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_2- G-; T_J = 25^\circ\text{C}$; Fig. 8		-	3	25	mA
		$V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_2- G+; T_J = 25^\circ\text{C}$; Fig. 8		-	4	35	mA
I_H	holding current	$V_D = 12 \text{ V}; T_J = 25^\circ\text{C}$; Fig. 9		-	2.5	20	mA
V_T	on-state voltage	$I_T = 10 \text{ A}; T_J = 25^\circ\text{C}$; Fig. 10		-	1.3	1.65	V
V_{GT}	gate trigger voltage	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_J = 25^\circ\text{C}$; Fig. 11		-	0.7	1	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_J = 125^\circ\text{C}$; Fig. 11		0.25	0.4	-	V
I_D	off-state current	$V_D = 600 \text{ V}; T_J = 125^\circ\text{C}$		-	0.1	0.5	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 402 \text{ V}; T_J = 125^\circ\text{C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit		-	50	-	V/ μ s
t_{gt}	gate-controlled turn-on time	$I_{TM} = 12 \text{ A}; V_D = 600 \text{ V}; I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu\text{s}$		-	2	-	μ s

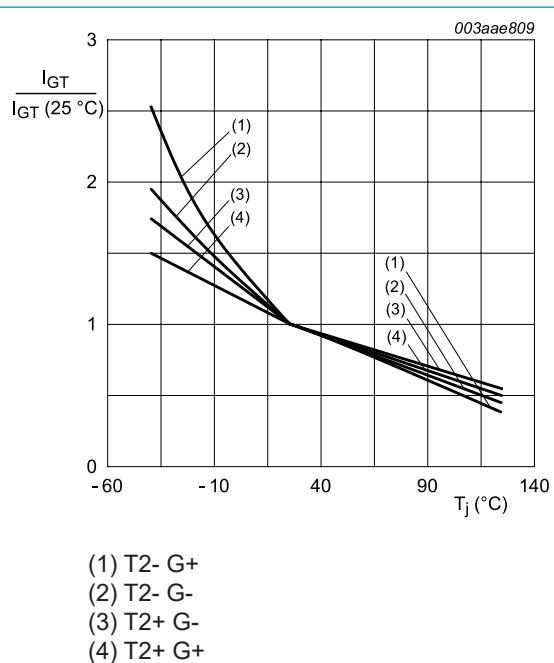


Fig. 7. Normalized gate trigger current as a function of junction temperature

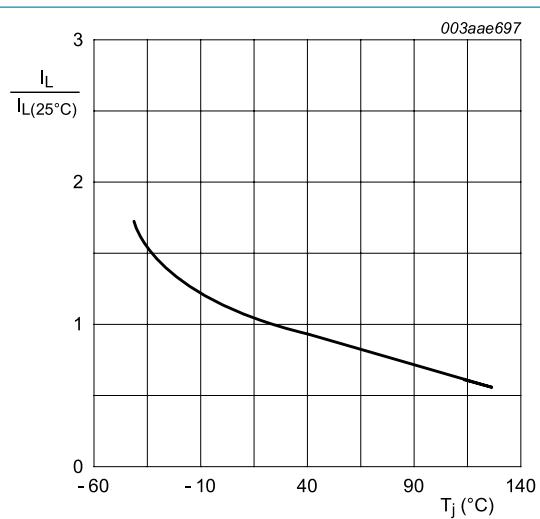


Fig. 8. Normalized latching current as a function of junction temperature

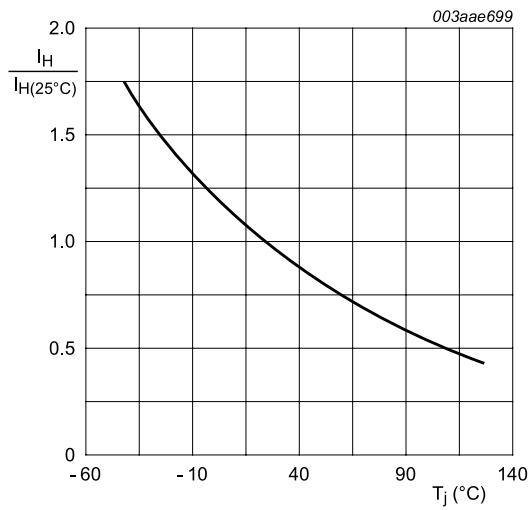
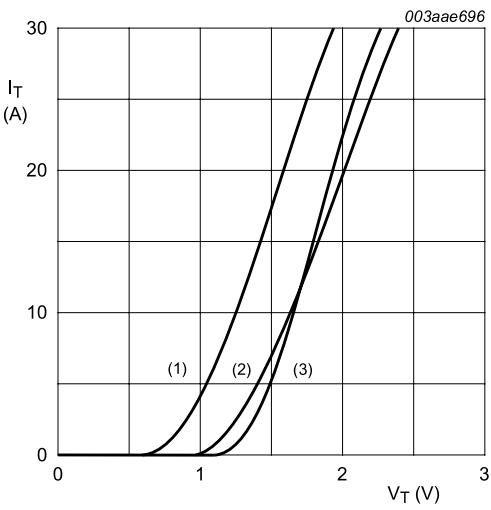


Fig. 9. Normalized holding current as a function of junction temperature



$$V_o = 1.264 \text{ V}; R_s = 0.038 \Omega$$

(1) $T_j = 125^{\circ}\text{C}$; typical values

(2) $T_j = 125^{\circ}\text{C}$; maximum values

(3) $T_j = 25^{\circ}\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage

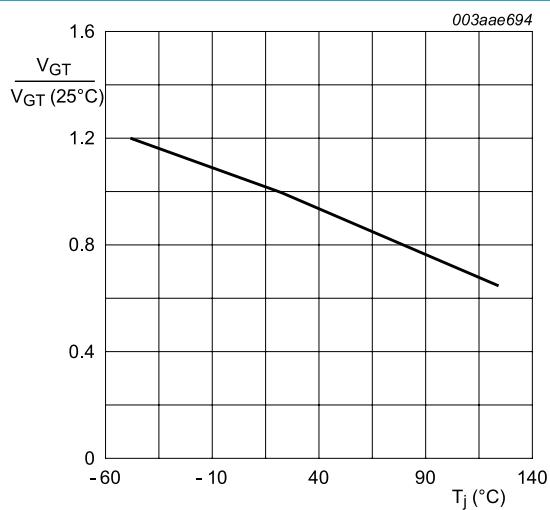
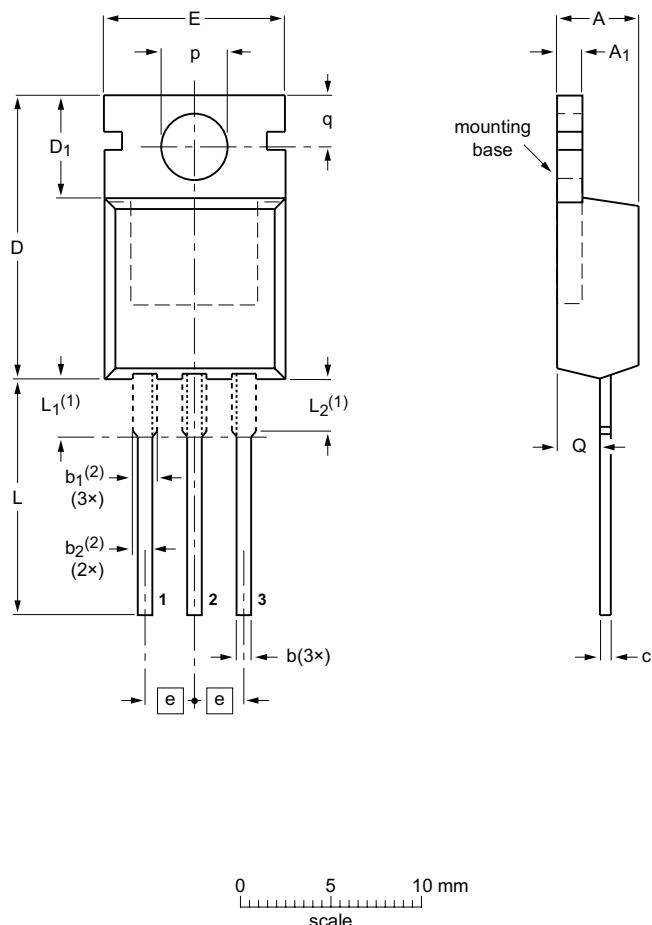


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

11. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	b ₁ ⁽²⁾	b ₂ ⁽²⁾	c	D	D ₁	E	e	L	L ₁ ⁽¹⁾	L ₂ ⁽¹⁾ max.	p	q	Q
mm	4.7	1.40	0.9	1.6	1.3	0.7	16.0	6.6	10.3	2.54	15.0	3.30	3.0	3.8	3.0	2.6
	4.1	1.25	0.6	1.0	1.0	0.4	15.2	5.9	9.7		12.8	2.79		3.5	2.7	2.2

Notes

1. Lead shoulder designs may vary.
2. Dimension includes excess dambar.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT78		3-lead TO-220AB	SC-46			08-04-23 08-06-13

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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